

9.28.06

10-05-2006

FORM PTO-1595

(Rev. 10/02)

Docket No.: 070679-0181



103317835

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

To the Honorable Commissioner for Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of Conveying Party(ies):

Chae-kyu JANG

2. Name and address of receiving party(ies):

Name: HYNIX SEMICONDUCTOR INC.

Address: San 136-1, Ami-ri, Bubal-eub, Ichon-shi

Kyoungki-do, 467-860 Republic of Korea

Additional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

3. Nature of Conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: September 25, 2006

Additional name(s) & address(es) attached? ☐ Yes ☐ No

4. Application number(s) or patent number(s):

If the document is being filed together with a new application, the execution date of the application is: September 25, 2006

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached? ☐ Yes ☐ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL &amp; EMERY LLP

Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: D. C. Zip: 20005-3096

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)

\$40.00

☐ Enclosed☒ Authorized to be charged to deposit account

8. Deposit account number:

500417

DO NOT USE THIS SPACE

9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Stephen A. Becker, 26,527

September 28, 2006

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet: 2

OMB No. 0651-0027 (exp. 6/30/2005)

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PATENT  
REEL: 018361 FRAME: 0556

(SAB)

Docket No.: \_\_\_\_\_

**ASSIGNMENT**

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

**JANG, Chae-Kyu**

who has made a certain new and useful invention, hereby sells, assigns and transfers unto  
**Hynix Semiconductor Inc.**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

OVER-DRIVING CIRCUIT FOR SEMICONDUCTOR MEMORY DEVICE

(a) for which an application for United States Letters Patent was filed on \_\_\_\_\_, and identified by United States Serial No. \_\_\_\_\_; or

(b) for which an application for United States Letters Patent was executed on \_\_\_\_\_,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

INVENTOR

DATE SIGNED

  
Name: JANG, Chae-Kyu

September 25, 2006